

650-kHz/1.2-MHz 18.5-V STEP-UP DC-DC CONVERTER

Check for Samples: [TPS61085T](#)

FEATURES

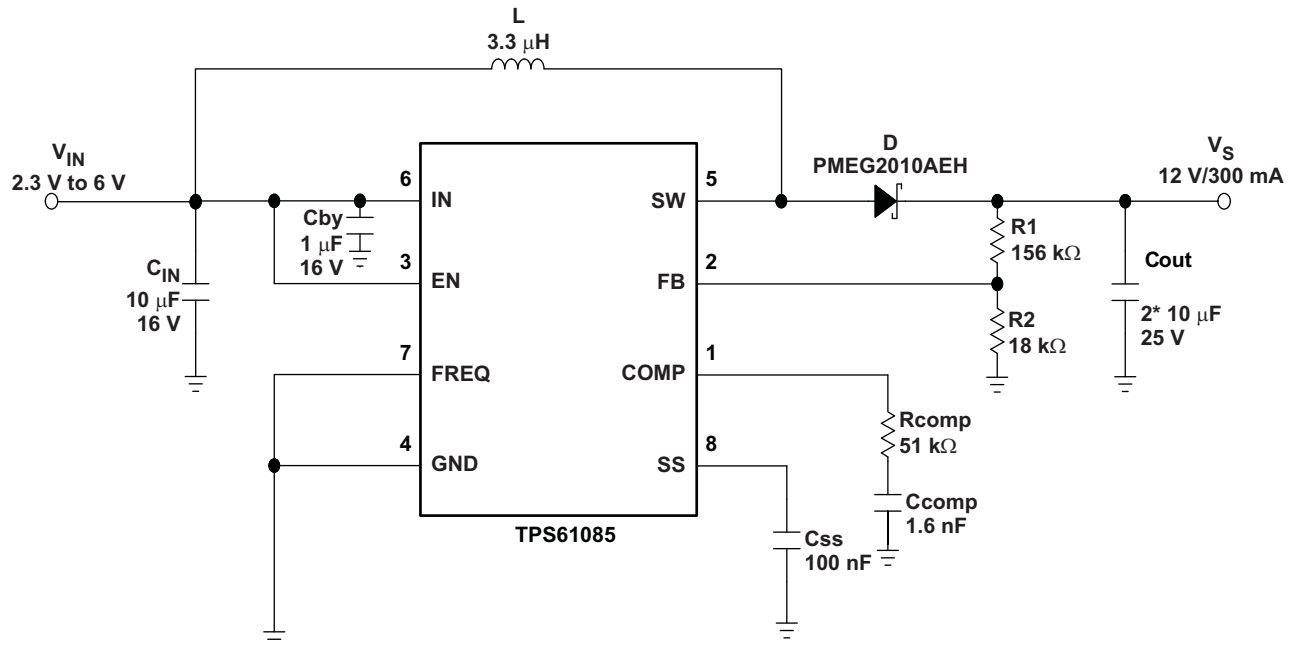
- 2.3-V to 6-V Input Voltage Range
- 18.5-V Boost Converter With 2.0-A Switch Current
- 650-kHz/1.2-MHz Selectable Switching Frequency
- Adjustable Soft-Start
- Thermal Shutdown
- Undervoltage Lockout
- 8-Pin MSOP Package

APPLICATIONS

- Handheld Devices
- GPS Receiver
- Digital Still Camera
- Portable Applications
- DSL Modem
- PCMCIA Card
- TFT LCD Bias Supply

DESCRIPTION

The TPS61085 is a high-frequency high-efficiency dc-to-dc converter with an integrated 2.0-A 0.13-Ω power switch capable of providing an output voltage up to 18.5 V. The selectable frequency of 650 kHz and 1.2 MHz allows the use of small external inductors and capacitors and provides fast transient response. The external compensation allows optimizing the application for specific conditions. A capacitor connected to the soft-start pin minimizes inrush current at startup.



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This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

ORDERING INFORMATION⁽¹⁾

| T _A | PACKAGE ⁽²⁾ | | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
|----------------|------------------------|--------------|-----------------------|------------------|
| –40°C to 105°C | MSOP-8 – DGK | Reel of 2500 | TPS61085TDGKR | PTQI |
| | TSSOP-8 – PW | Reel of 2000 | TPS61085TPWR | 61085T |

- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.
 (2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

| | VALUE | UNIT |
|---|------------------------------|------|
| Input voltage range I _N ⁽²⁾ | –0.3 to 7 | V |
| Voltage range on pins EN, FB, SS, FREQ, COMP | –0.3 to 7 | V |
| Voltage on pin SW | 20 | V |
| ESD rating HBM | 2 | kV |
| ESD rating MM | 200 | V |
| ESD rating CDM | 500 | V |
| Continuous power dissipation | See Dissipation Rating Table | |
| Operating junction temperature range | –40 to 150 | °C |
| Storage temperature range | –65 to 150 | °C |
| Lead temperature (soldering, 10 sec) | 260 | °C |

- (1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
 (2) All voltage values are with respect to network ground terminal.

DISSIPATION RATINGS^{(1) (2)}

| PACKAGE | R _{θJA} | T _A ≤ 25°C POWER RATING | T _A = 70°C POWER RATING | T _A = 105°C POWER RATING |
|---------|------------------|---------------------------------------|---------------------------------------|--|
| MSOP | 181°C/W | 552 mW | 303 mW | 110 mW |
| TSSOP | 160°C/W | 625 mW | 343 mW | 125 mW |

(1) $P_D = (T_J - T_A) / R_{\theta JA}$

(2) R_{θJA} given for High-K PCB board

RECOMMENDED OPERATING CONDITIONS

| | MIN | TYP | MAX | UNIT |
|---|-----------------------|-----|------|------|
| V _{IN} Input voltage range | 2.3 | | 6 | V |
| V _S Boost output voltage range | V _{IN} + 0.5 | | 18.5 | V |
| T _A Operating free-air temperature | –40 | | 105 | °C |
| T _J Operating junction temperature | –40 | | 125 | °C |

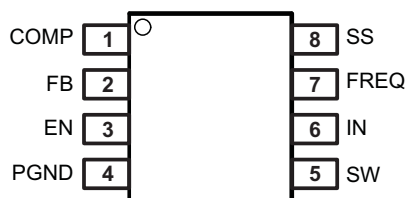
ELECTRICAL CHARACTERISTICS

 $V_{IN} = 3.3\text{ V}$, $EN = IN$, $V_S = 12\text{ V}$, $T_A = -40^{\circ}\text{C}$ to 105°C , typical values are at $T_A = 25^{\circ}\text{C}$ (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|-------------------------------|-------------------------------------|--|----------------|--------|-------|---------------------|
| SUPPLY | | | | | | |
| V_{IN} | Input voltage range | | 2.3 | | 6 | V |
| I_Q | Operating quiescent current into IN | Device not switching, $V_{FB} = 1.3\text{ V}$ | | 70 | 100 | μA |
| I_{SDVIN} | Shutdown current into IN | $EN = \text{GND}$ | | | 1 | μA |
| UVLO | Undervoltage lockout threshold | V_{IN} falling | | | 2.2 | V |
| | | V_{IN} rising | | | 2.3 | V |
| T_{SD} | Thermal shutdown | Temperature rising | | 150 | | $^{\circ}\text{C}$ |
| $T_{SD(HYS)}$ | Thermal shutdown hysteresis | | | 14 | | $^{\circ}\text{C}$ |
| LOGIC SIGNALS EN, FREQ | | | | | | |
| V_{IH} | High level input voltage | $V_{IN} = 2.3\text{ V}$ to 6 V | 2 | | | V |
| V_{IL} | Low level input voltage | $V_{IN} = 2.3\text{ V}$ to 6 V | | | 0.5 | V |
| I_{lkg} | Input leakage current | $EN = \text{FREQ} = \text{GND}$ | | | 0.1 | μA |
| BOOST CONVERTER | | | | | | |
| V_S | Boost output voltage | | $V_{IN} + 0.5$ | | 18.5 | V |
| V_{FB} | Feedback regulation voltage | | 1.230 | 1.238 | 1.246 | V |
| gm | Transconductance error amplifier | | | 107 | | $\mu\text{A/V}$ |
| I_{FB} | Feedback input bias current | $V_{FB} = 1.238\text{ V}$ | | | 0.1 | μA |
| $R_{DS(on)}$ | N-channel MOSFET on-resistance | $V_{IN} = V_{GS} = 5\text{ V}$, $I_{SW} = \text{current limit}$ | | 0.13 | 0.20 | Ω |
| | | $V_{IN} = V_{GS} = 3.3\text{ V}$, $I_{SW} = \text{current limit}$ | | 0.15 | 0.24 | |
| I_{lkg} | SW leakage current | $EN = \text{GND}$, $V_{SW} = 6\text{ V}$ | | | 10 | $\hat{\mu}\text{A}$ |
| I_{LIM} | N-Channel MOSFET current limit | | 2.0 | 2.6 | 3.2 | A |
| I_{SS} | Soft-start current | $V_{SS} = 1.238\text{ V}$ | 7 | 10 | 13 | μA |
| f_{osc} | Oscillator frequency | FREQ = high | 0.9 | 1.2 | 1.5 | MHz |
| | | FREQ = low | 480 | 650 | 820 | kHz |
| | Line regulation | $V_{IN} = 2.3\text{ V}$ to 6 V , $I_{OUT} = 10\text{ mA}$ | | 0.0002 | | %/V |
| | Load regulation | $V_{IN} = 3.3\text{ V}$, $I_{OUT} = 1\text{ mA}$ to 400 mA | | 0.11 | | %/A |

PIN ASSIGNMENT

DGK, PW PACKAGES (TOP VIEW)



8-PIN 4.9mm x 3mm x 1.1mm MSOP (DGK)
8-PIN 6.4mm x 3mm x 1.2mm TSSOP (PW)

TERMINAL FUNCTIONS

| TERMINAL | | I/O | DESCRIPTION |
|----------|-----|-----|--|
| NAME | NO. | | |
| COMP | 1 | I/O | Compensation pin |
| FB | 2 | I | Feedback pin |
| EN | 3 | I | Shutdown control input. Connect this pin to logic high level to enable the device |
| PGND | 4 | | Power ground |
| SW | 5 | | Switch pin |
| IN | 6 | | Input supply pin |
| FREQ | 7 | I | Frequency select pin. The power switch operates at 650 kHz if FREQ is connected to GND and at 1.2 MHz if FREQ is connected to IN |
| SS | 8 | | Soft-start control pin. Connect a capacitor to this pin if soft-start needed. Open = no soft-start |

TYPICAL CHARACTERISTICS

TABLE OF GRAPHS

| | | | FIGURE |
|--------|--|--|-----------|
| η | Efficiency | vs Load current, $V_S = 12\text{ V}$, $V_{IN} = 3.3\text{ V}$ | Figure 1 |
| η | Efficiency | vs Load current, $V_S = 9\text{ V}$, $V_{IN} = 3.3\text{ V}$ | Figure 2 |
| | PWM switching - discontinuous conduction | | Figure 3 |
| | PWM switching - continuous conduction | | Figure 4 |
| | Load transient response | at High frequency | Figure 5 |
| | Load transient response | at Low frequency | Figure 6 |
| | Soft-start | | Figure 7 |
| | Supply current | vs Supply voltage | Figure 8 |
| | Frequency | vs Load current | Figure 9 |
| | Frequency | vs Supply voltage | Figure 10 |

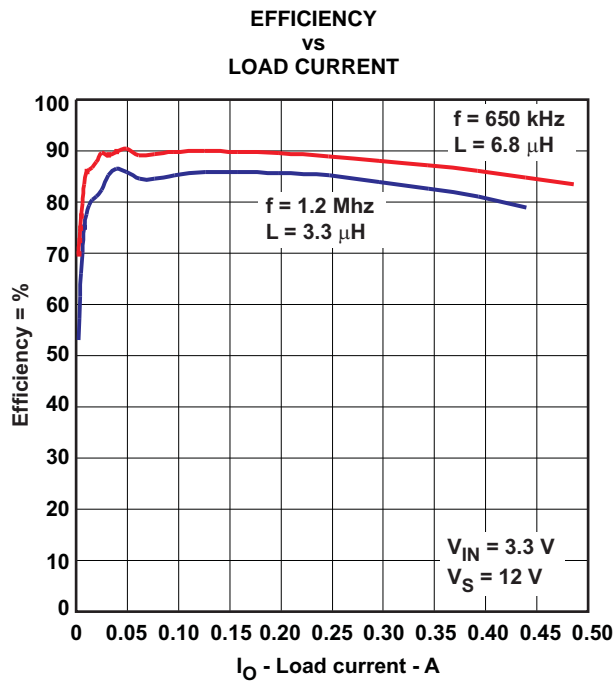


Figure 1.

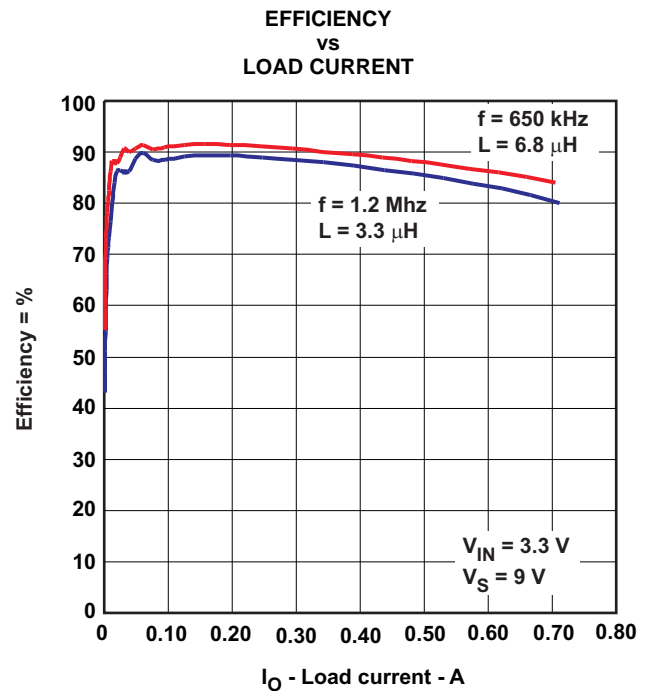


Figure 2.

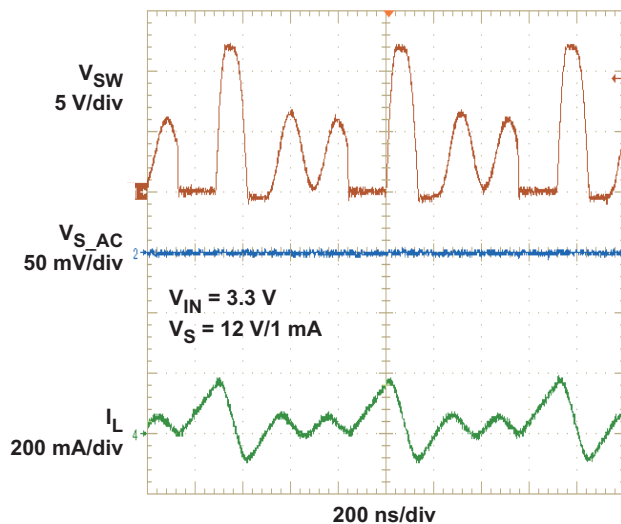
**PWM SWITCHING
DISCONTINUOUS CONDUCTION MODE**


Figure 3.

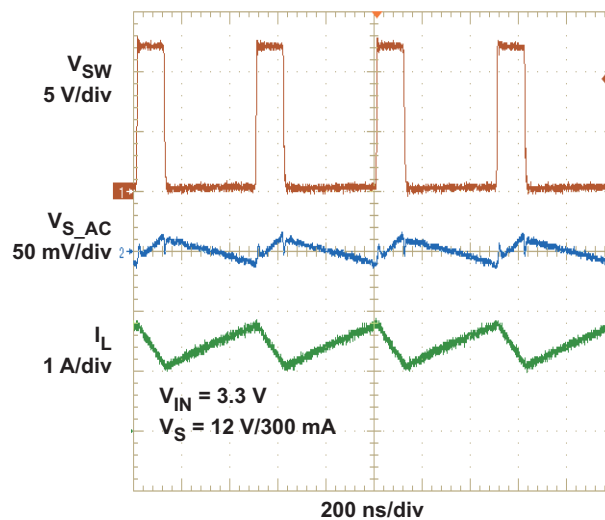
**PWM SWITCHING
CONTINUOUS CONDUCTION MODE**


Figure 4.

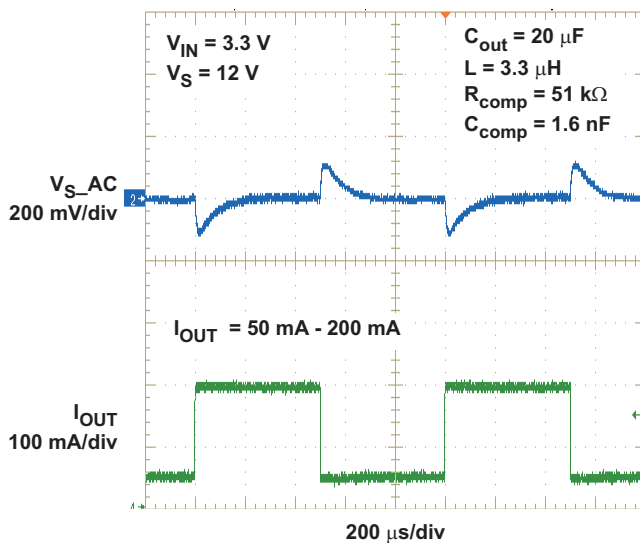
**LOAD TRANSIENT RESPONSE
HIGH FREQUENCY (1.2 MHz)**


Figure 5.

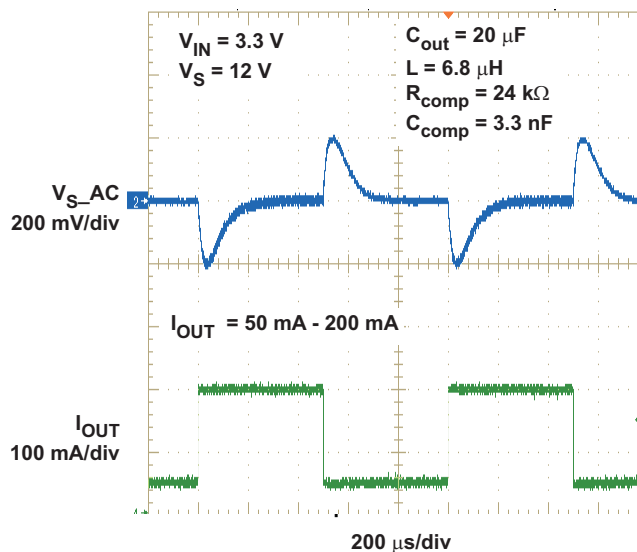
**LOAD TRANSIENT RESPONSE
LOW FREQUENCY (650 kHz)**


Figure 6.

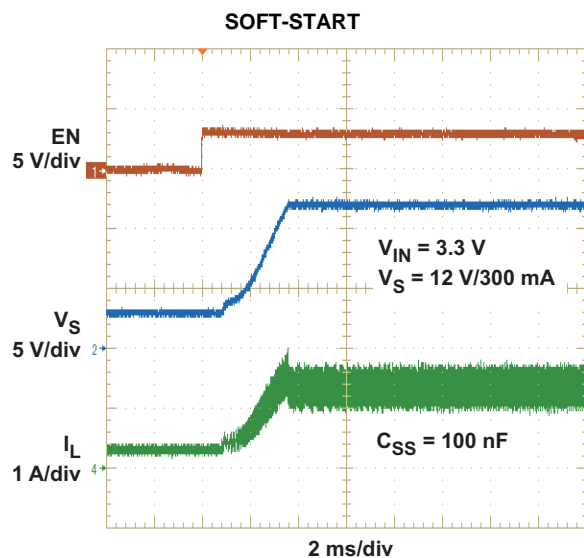


Figure 7.

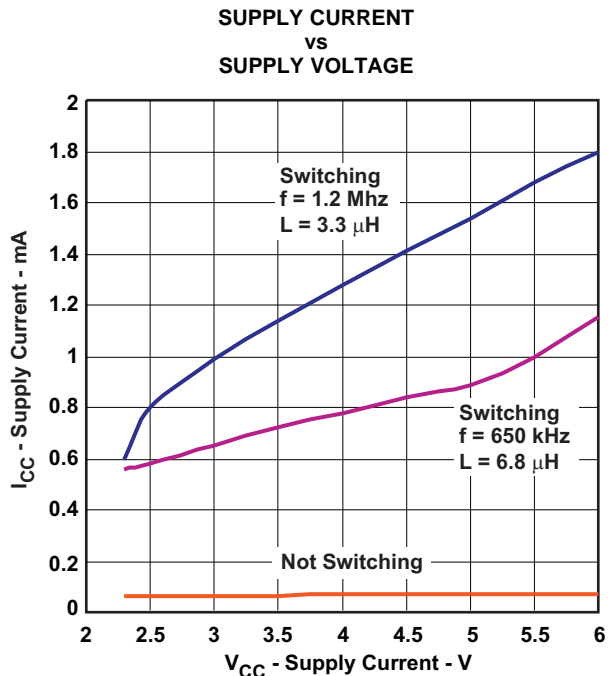


Figure 8.

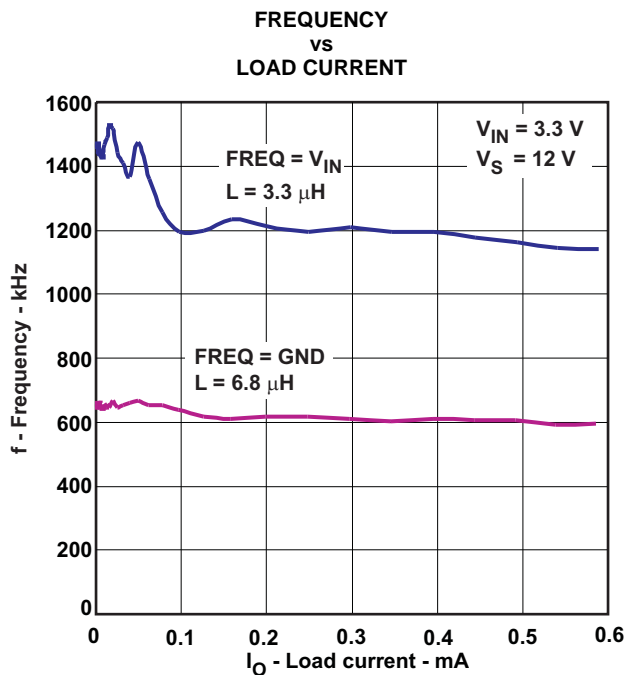


Figure 9.

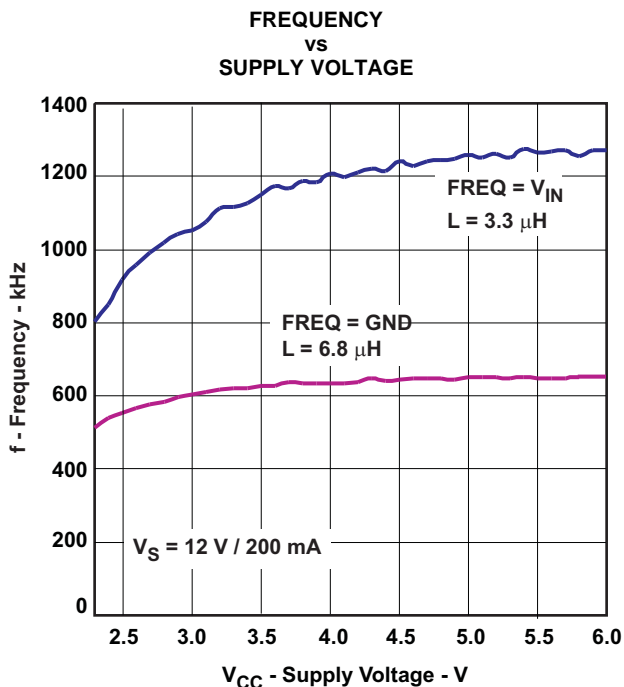


Figure 10.

DETAILED DESCRIPTION

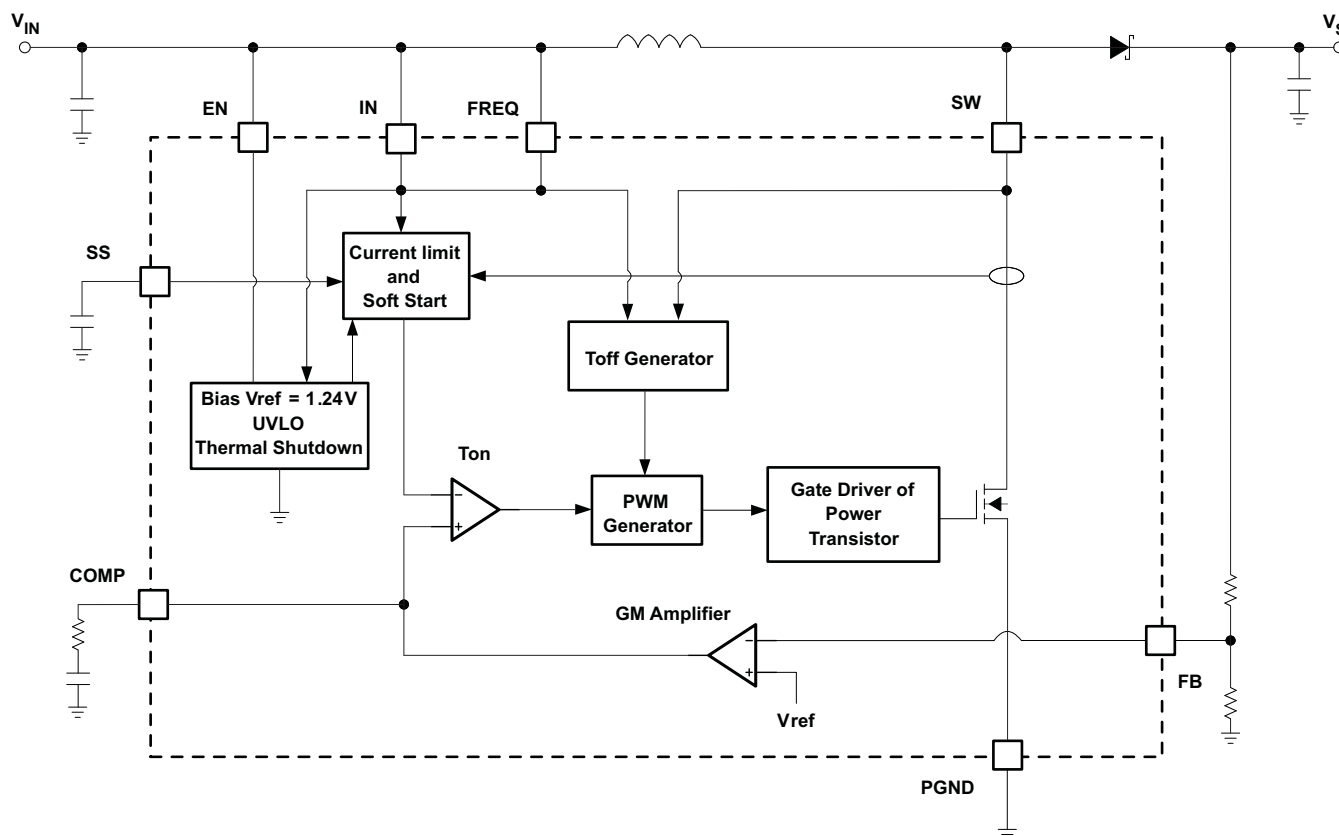


Figure 11. Block Diagram

The boost converter is designed for output voltages up to 18.5 V with a switch peak current limit of 2.0 A minimum. The device, which operates in a current mode scheme with quasi-constant frequency, is externally compensated for maximum flexibility and stability. The switching frequency is selectable between 650 kHz and 1.2 MHz and the minimum input voltage is 2.3 V. To control the inrush current at start-up a soft-start pin is available.

During the on-time, the voltage across the inductor causes the current in it to rise. When the current reaches a threshold value set by the internal GM amplifier, the power transistor is turned off, the energy stored into the inductor is then released and the current flows through the Schottky diode towards the output of the boost converter. The off-time is fixed for a certain V_{IN} and V_S , and therefore maintains the same frequency when varying these parameters.

However, for different output loads, the frequency may slightly change due to the voltage drop across the $R_{ds(on)}$ of the power transistor which will have an effect on the voltage across the inductor and thus on t_{ON} (t_{OFF} remains fixed). Some slight frequency changes might also appear with a fixed output load due to the fact that the output voltage V_S is not sensed directly but via the SW Pin, which affects accuracy.

Because of the quasi-constant frequency behavior of the device, the TPS61085 eliminates the need for an internal oscillator and slope compensation, which provides better stability for the system over a wide of input and output voltages range, and more stable and accurate current limiting operation compared to boost converters operating with a conventional PWM scheme. The TPS61085 topology has also the benefits of providing very good load and line regulations, and excellent load transient response.

Design Procedure

The first step in the design procedure is to verify that the maximum possible output current of the boost converter supports the specific application requirements. A simple approach is to estimate the converter efficiency, by taking the efficiency numbers from the provided efficiency curves or to use a worst case assumption for the expected efficiency, e.g. 90%.

$$D = 1 - \frac{V_{IN} \times \eta}{V_S}$$

1. Duty Cycle:

$$I_{out} = \left(I_{swpeak} - \frac{\Delta I_L}{2} \right) \times (1 - D)$$

2. Maximum output current:

$$I_{swpeak} = \frac{\Delta I_L}{2} + \frac{I_{out}}{1 - D}$$

3. Peak switch current:

$$\Delta I_L = \frac{V_{IN} \times D}{f_s \times L}$$

with

and

I_{swpeak} = converter switch current (minimum switch current limit = 2.0 A)

f_s = Converter switching frequency (typically 1.2 MHz)

L = Selected inductor value

η = Estimated converter efficiency (please use the number from the efficiency plots or 90% as an estimation)

ΔI_L = Inductor peak-to-peak ripple current

The peak switch current is the steady state peak switch current that the integrated switch, inductor and external Schottky diode has to be able to handle. The calculation must be done for the minimum input voltage where the peak switch current is the highest.

Soft-start

The boost converter has an adjustable soft-start to prevent high inrush current during start-up. To minimize the inrush current during start-up an external capacitor connected to the soft-start pin SS is used to slowly ramp up the internal current limit of the boost converter when charged with a constant current. When the EN pin is pulled high, the soft-start capacitor C_{SS} is immediately charged to 0.3 V. The capacitor is then charged at a constant current of 10 μ A typically until the output of the boost converter V_S has reached its Power Good threshold (90% of V_S nominal value). During this time, the SS voltage directly controls the peak inductor current, starting with 0 A at $V_{SS} = 0.3$ V up to the full current limit at $V_{SS} \approx 800$ mV. The maximum load current is available after the soft-start is completed. The larger the capacitor the slower the ramp of the current limit and the longer the soft-start time. A 100 nF capacitor is usually sufficient for most of the applications. When the EN pin is pulled low, the soft-start capacitor is discharged to ground.

Inductor Selection

The TPS61085 is designed to work with a wide range of inductors. The main parameter for the inductor selection is the saturation current of the inductor which should be higher than the peak switch current as calculated in the *Design Procedure* section with additional margin to cover for heavy load transients. An alternative, more conservative, is to choose an inductor with a saturation current at least as high as the maximum switch current limit of 3.2 A. The other important parameter is the inductor dc resistance. Usually, the lower the dc resistance the higher the efficiency. It is important to note that the inductor dc resistance is not the only parameter determining the efficiency. Especially for a boost converter where the inductor is the energy storage element, the type and core material of the inductor influences the efficiency as well. At high switching frequencies of 1.2 MHz inductor core losses, proximity effects and skin effects become more important. Usually, an inductor with a larger form factor gives higher efficiency. The efficiency difference between different inductors can vary between 2% to 10%. For the TPS61085, inductor values between 3 μ H and 6 μ H are a good choice with a switching frequency of 1.2 MHz, typically 3.3 μ H. At 650 kHz we recommend inductors between 6 μ H and 13 μ H, typically 6.8 μ H. Possible inductors are shown in [Table 1](#).

Typically, it is recommended that the inductor current ripple is below 20% of the average inductor current. The following equation can therefore be used to calculate the inductor value:

$$L = \left(\frac{V_{IN}}{V_S} \right)^2 \times \left(\frac{V_S - V_{IN}}{I_{out_max} \times f} \right) \times \left(\frac{\eta}{0.35} \right) \quad (1)$$

Table 1. Inductor Selection

| L (μH) | SUPPLIER | COMPONENT CODE | SIZE (L×W×H mm) | DCR TYP (mΩ) | Isat (A) |
|----------------|------------------|-------------------|--------------------|-----------------|----------|
| 1.2 MHz | | | | | |
| 3.3 | Sumida | CDH38D09 | 4 × 4 × 1 | 240 | 1.25 |
| 4.7 | Sumida | CDPH36D13 | 5 × 5 × 1.5 | 155 | 1.36 |
| 3.3 | Sumida | CDPH4D19F | 5.2 × 5.2 × 2 | 33 | 1.5 |
| 3.3 | Sumida | CDRH6D12 | 6.7 × 6.7 × 1.5 | 62 | 2.2 |
| 4.7 | Würth Elektronik | 7447785004 | 5.9 × 6.2 × 3.3 | 60 | 2.5 |
| 5 | Coilcraft | MSS7341 | 7.3 × 7.3 × 4.1 | 24 | 2.9 |
| 650 kHz | | | | | |
| 6.8 | Sumida | CDP14D19 | 5.2 × 5.2 × 2 | 50 | 1 |
| 10 | Coilcraft | LPS4414 | 4.3 × 4.3 × 1.4 | 380 | 1.2 |
| 6.8 | Sumida | CDRH6D12/LD | 6.7 × 6.7 × 1.5 | 95 | 1.25 |
| 10 | Sumida | CDR6D23 | 5 × 5 × 2.4 | 133 | 1.75 |
| 10 | Würth Elektronik | 744778910 | 7.3 × 7.3 × 3.2 | 51 | 2.2 |
| 6.8 | Sumida | CDRH6D26HP | 7 × 7 × 2.8 | 52 | 2.9 |

Rectifier Diode Selection

To achieve high efficiency, a Schottky type should be used for the rectifier diode. The reverse voltage rating should be higher than the maximum output voltage of the converter. The averaged rectified forward current I_{avg} , the Schottky diode needs to be rated for, is equal to the output current I_{out} :

$$I_{avg} = I_{out} \quad (2)$$

Usually a Schottky diode with 2 A maximum average rectified forward current rating is sufficient for most applications. The Schottky rectifier can be selected with lower forward current capability depending on the output current I_{out} but has to be able to dissipate the power. The dissipated power is the average rectified forward current times the diode forward voltage.

$$P_D = I_{avg} \times V_{forward}$$

Typically the diode should be able to dissipate around 500mW depending on the load current and forward voltage.

Table 2. Rectifier Diode Selection

| CURRENT RATING I_{avg} | Vr | V _{forward} / I_{avg} | SUPPLIER | COMPONENT CODE | PACKAGE TYPE |
|-----------------------------|------|----------------------------------|-------------------------|-------------------|------------------------|
| 750 mA | 20 V | 0.425 V / 750 mA | Fairchild Semiconductor | FYV0704S | SOT 23 |
| 1 A | 20 V | 0.39 V / 1 A | NXP | PMEG2010AEH | SOD 123 |
| 1 A | 20 V | 0.52 V / 1 A | Vishay Semiconductor | B120 | SMA |
| 1 A | 20 V | 0.5 V / 1 A | Vishay Semiconductor | SS12 | SMA |
| 1 A | 20 V | 0.44 V / 1 A | Vishay Semiconductor | MSS1P2L | μ-SMP (Low Profile) |

Setting the Output Voltage

The output voltage is set by an external resistor divider. Typically, a minimum current of 50 μ A flowing through the feedback divider gives good accuracy and noise covering. A standard low side resistor of 18 k Ω is typically selected. The resistors are then calculated as:

$$R2 = \frac{V_{ref}}{70\mu A} \approx 18k\Omega \quad R1 = R2 \times \left(\frac{V_S}{V_{ref}} - 1 \right) \quad (3)$$

Compensation (COMP)

The regulator loop can be compensated by adjusting the external components connected to the COMP pin. The COMP pin is the output of the internal transconductance error amplifier. Standard values of $R_{COMP} = 13$ k Ω and $C_{COMP} = 3.3$ nF will work for the majority of the applications.

Please refer to [Table 3](#) for dedicated compensation networks giving an improved load transient response. The following equations can be used to calculate R_{COMP} and C_{COMP} :

$$R_{COMP} = \frac{125 \times V_{IN} \times V_S \times C_{out}}{L \times I_{out_max}} \quad C_{COMP} = \frac{V_S \times C_{out}}{5 \times I_{out_max} \times R_{COMP}} \quad (4)$$

Table 3. Recommended Compensation Network Values at High/Low Frequency

| FREQUENCY | L | V _S | V _{IN} \pm 20% | R _{COMP} | C _{COMP} |
|----------------|-------------|----------------|---------------------------|-------------------|-------------------|
| High (1.2 MHz) | 3.3 μ H | 15 V | 5 V | 82 k Ω | 1.1 nF |
| | | | 3.3 V | 75 k Ω | 1.6 nF |
| | | 12 V | 5 V | 51 k Ω | 1.1 nF |
| | | | 3.3 V | 47 k Ω | 1.6 nF |
| | | 9 V | 5 V | 30 k Ω | 1.1 nF |
| | | | 3.3 V | 27 k Ω | 1.6 nF |
| Low (650 kHz) | 6.8 μ H | 15 V | 5 V | 43 k Ω | 2.2 nF |
| | | | 3.3 V | 39 k Ω | 3.3 nF |
| | | 12 V | 5 V | 27 k Ω | 2.2 nF |
| | | | 3.3 V | 24 k Ω | 3.3 nF |
| | | 9 V | 5 V | 15 k Ω | 2.2 nF |
| | | | 3.3 V | 13 k Ω | 3.3 nF |

[Table 3](#) gives conservatives Rcomp and Comp values for certain inductors, input and output voltages providing a very stable system. For a faster response time, a higher Rcomp value can be used to enlarge the bandwidth, as well as a slightly lower value of Ccomp to keep enough phase margin. These adjustments should be performed in parallel with the load transient response monitoring of TPS61085.

Input Capacitor Selection

For good input voltage filtering low ESR ceramic capacitors are recommended. TPS61085 has an analog input IN. Therefore, a 1 μ F bypass is highly recommended as close as possible to the IC from IN to GND.

One 10 μ F ceramic input capacitors are sufficient for most of the applications. For better input voltage filtering this value can be increased. Refer to [Table 4](#) and typical applications for input capacitor recommendations.

Output Capacitor Selection

For best output voltage filtering a low ESR output capacitor like ceramic capacitor is recommended. Two 10 μF ceramic output capacitors (or one 22 μF) work for most of the applications. Higher capacitor values can be used to improve the load transient response. Refer to [Table 4](#) for the selection of the output capacitor.

Table 4. Rectifier Input and Output Capacitor Selection

| | CAPACITOR | VOLTAGE RATING | SUPPLIER | COMPONENT CODE |
|------------------|-----------------------|----------------|-------------|-----------------|
| C_{IN} | 10 $\mu\text{F}/1206$ | 16 V | Taiyo Yuden | EMK212 BJ 106KG |
| IN bypass | 1 $\mu\text{F}/0603$ | 16 V | Taiyo Yuden | EMK107 BJ 105KA |
| C_{OUT} | 10 $\mu\text{F}/1206$ | 25 V | Taiyo Yuden | TMK316 BJ 106KL |

Frequency Select Pin (FREQ)

The frequency select pin FREQ allows to set the switching frequency of the device to 650 kHz (FREQ = low) or 1.2 MHz (FREQ = high). Higher switching frequency improves load transient response but reduces slightly the efficiency. The other benefits of higher switching frequency are a lower output ripple voltage. Usually, it is recommended to use 1.2 MHz switching frequency unless light load efficiency is a major concern.

Undervoltage Lockout (UVLO)

To avoid mis-operation of the device at low input voltages an undervoltage lockout is included that disables the device, if the input voltage falls below 2.2 V.

Thermal Shutdown

A thermal shutdown is implemented to prevent damages due to excessive heat and power dissipation. Typically the thermal shutdown threshold is 150°C. When the thermal shutdown is triggered the device stops switching until the temperature falls below typically 136°C. Then the device starts switching again.

APPLICATION INFORMATION

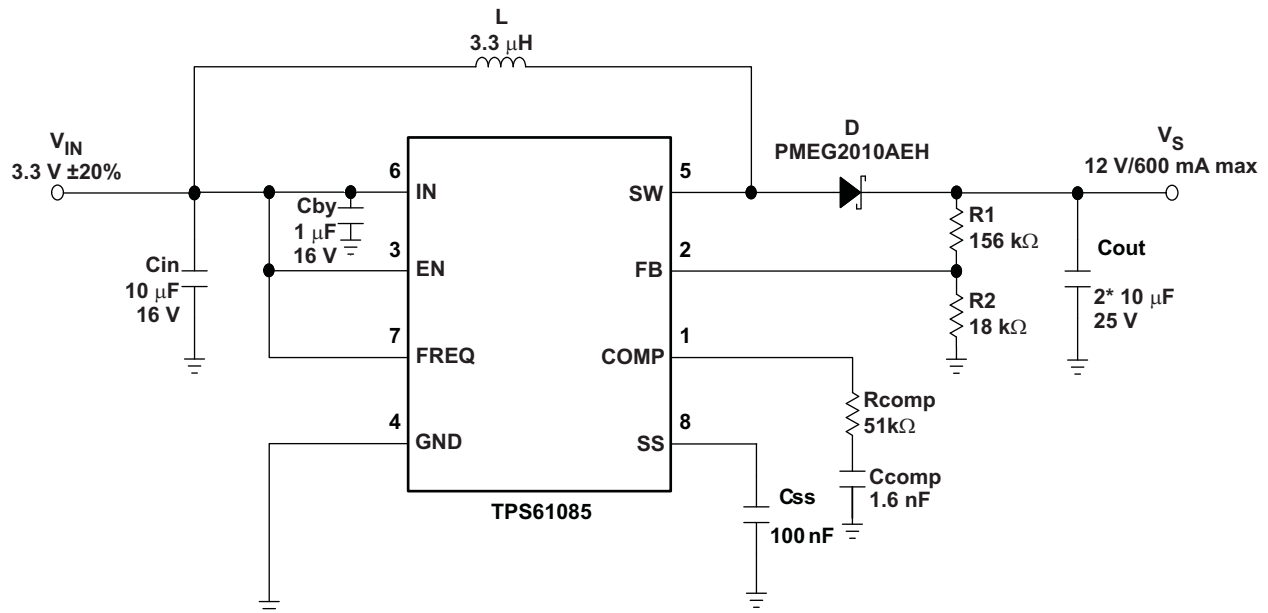


Figure 12. Typical Application, 3.3 V to 12 V ($f_{sw} = 1.2$ MHz)

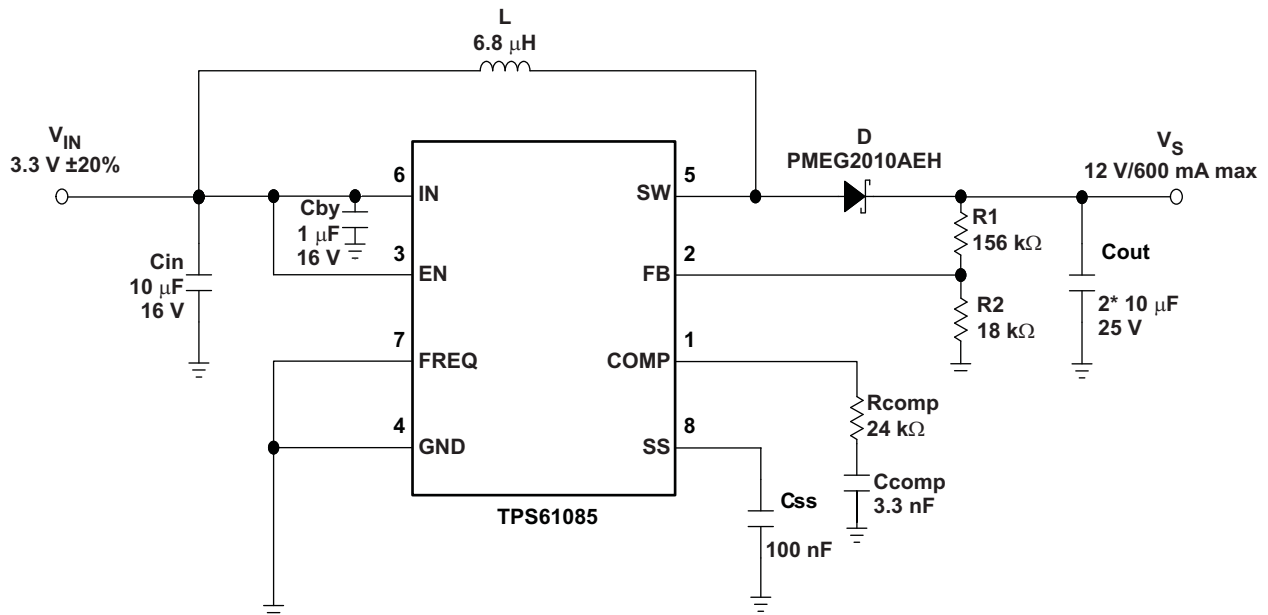


Figure 13. Typical Application, 3.3 V to 12 V ($f_{sw} = 650$ kHz)

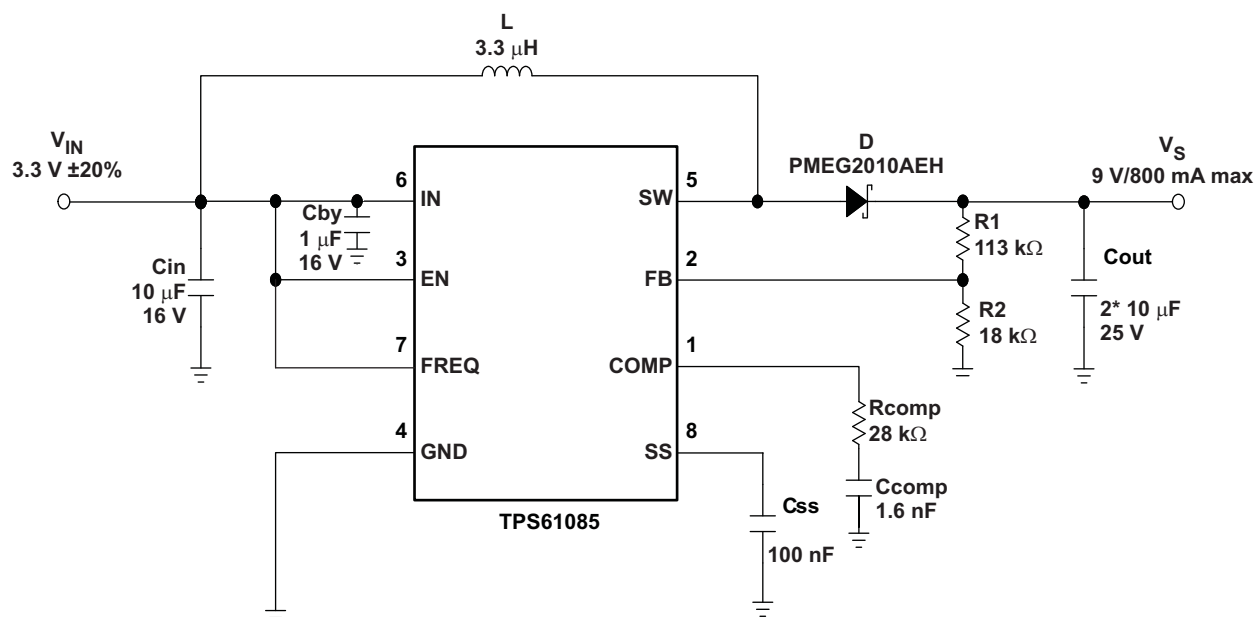


Figure 14. Typical Application, 3.3 V to 9 V ($f_{sw} = 1.2$ MHz)

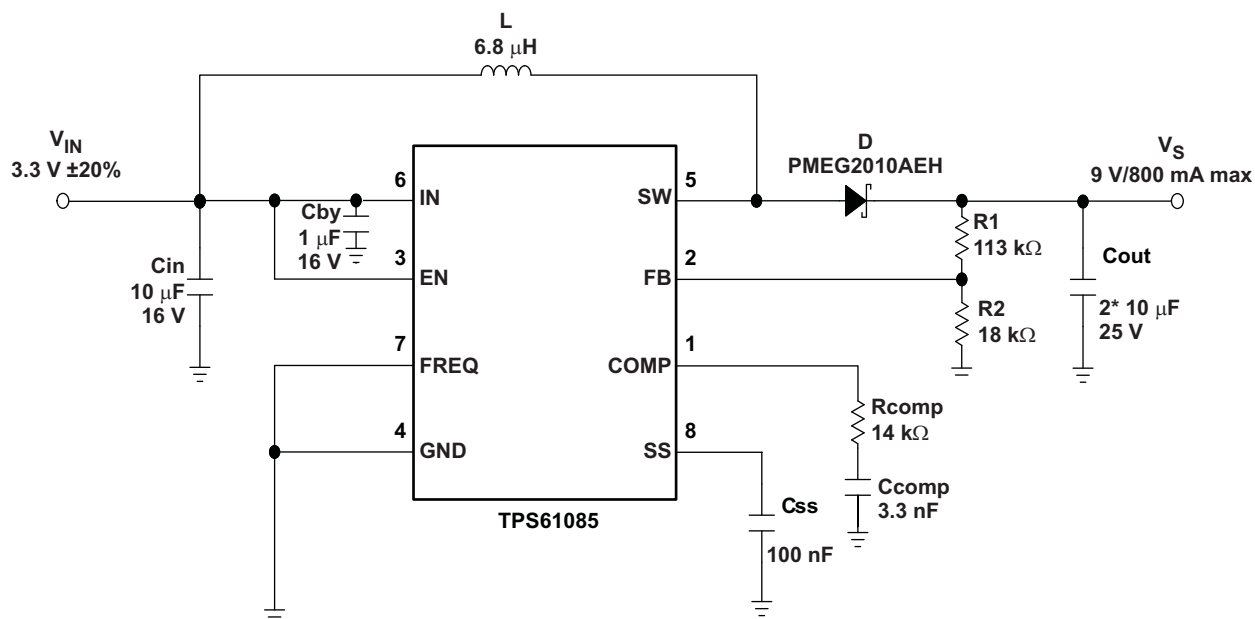


Figure 15. Typical Application, 3.3 V to 9 V ($f_{sw} = 650$ kHz)

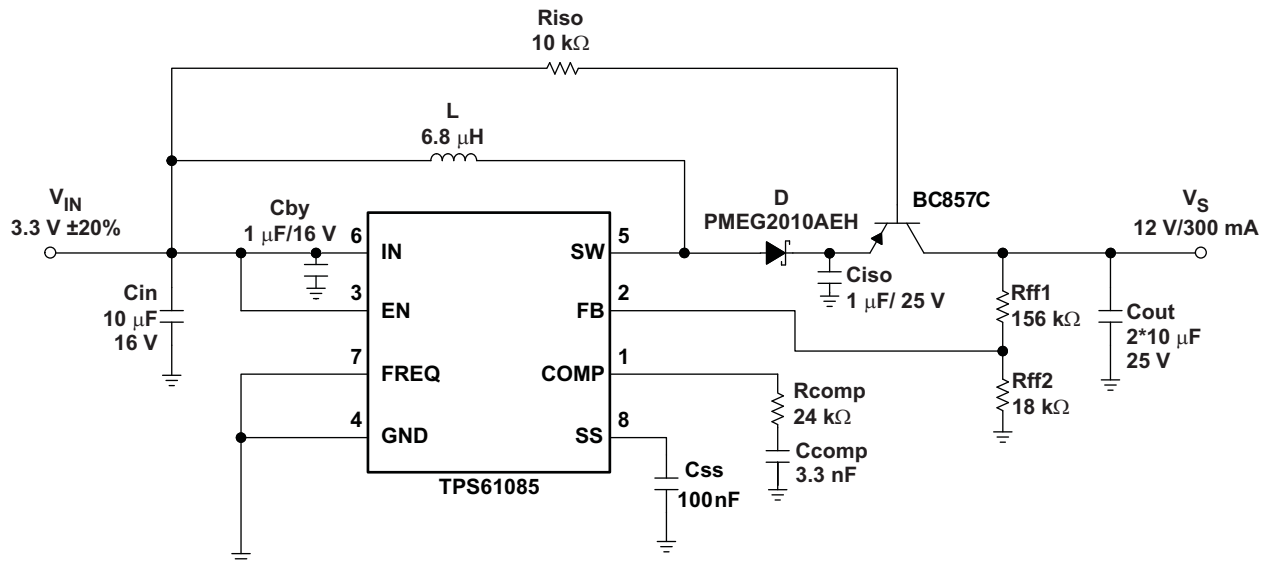


Figure 16. Typical Application with External Load Disconnect Switch

TFT LCD APPLICATION

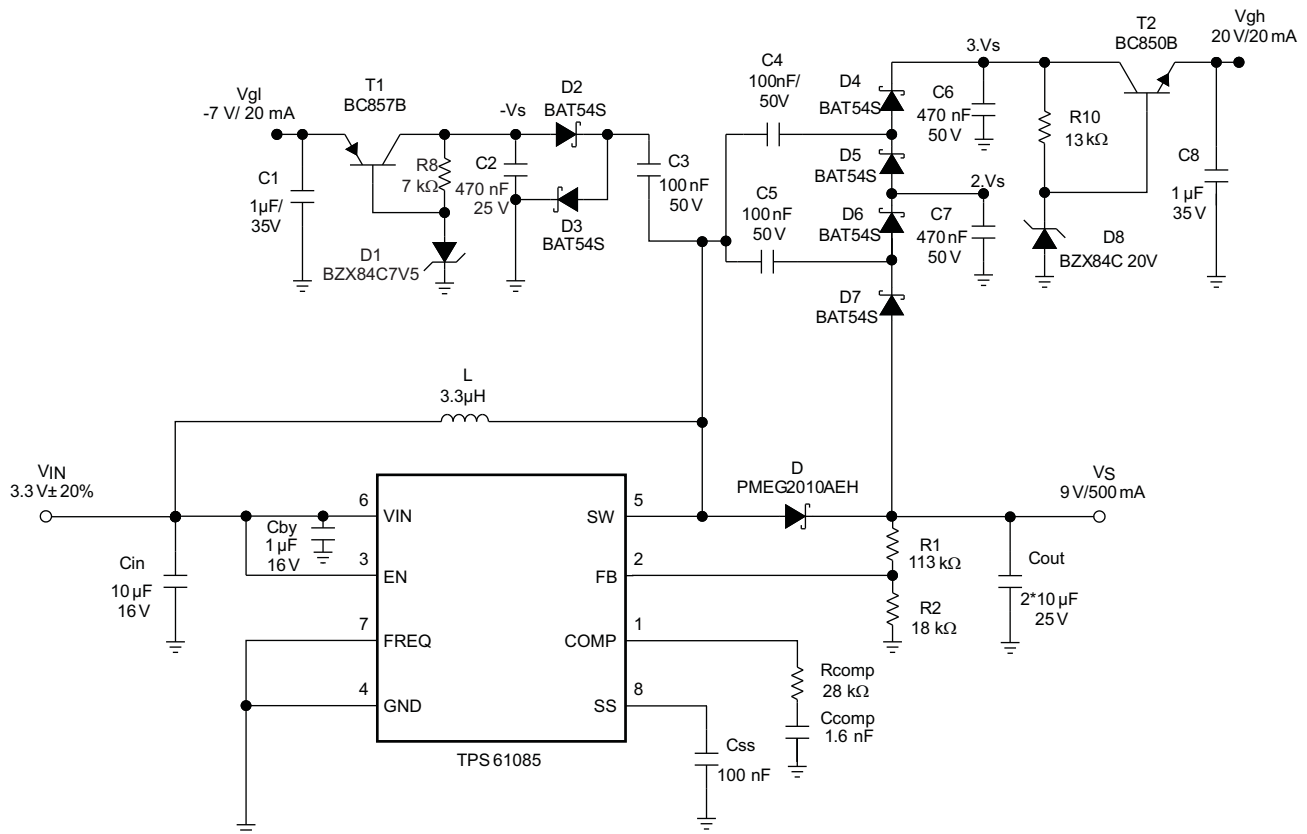


Figure 17. Typical Application 3.3 V to 9 V ($f_{sw} = 1.2$ MHz) for TFT LCD with External Charge Pumps (VGH, VGL)

WHITE LED APPLICATIONS

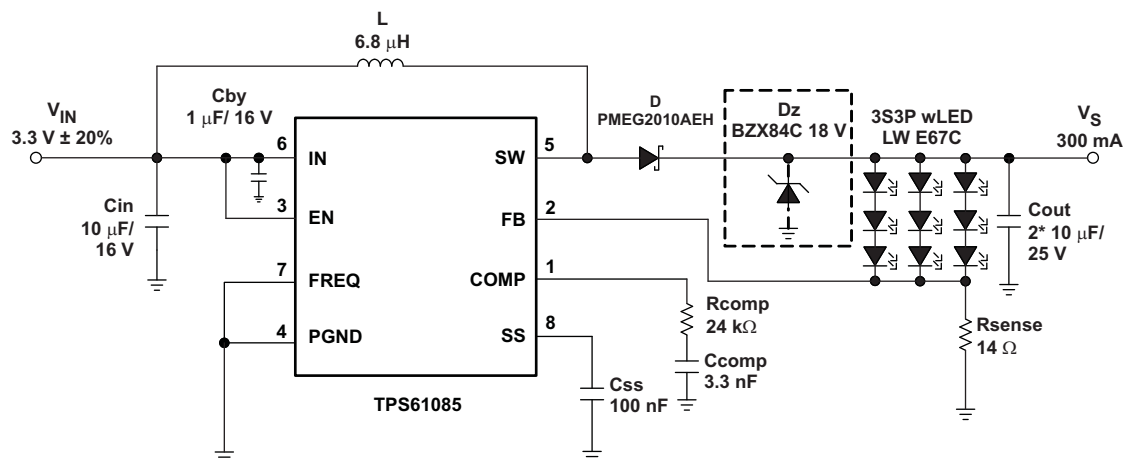


Figure 18. Simple Application (3.3V input - $f_{sw} = 650$ kHz) for wLED Supply (3S3P) (with optional clamping Zener diode)

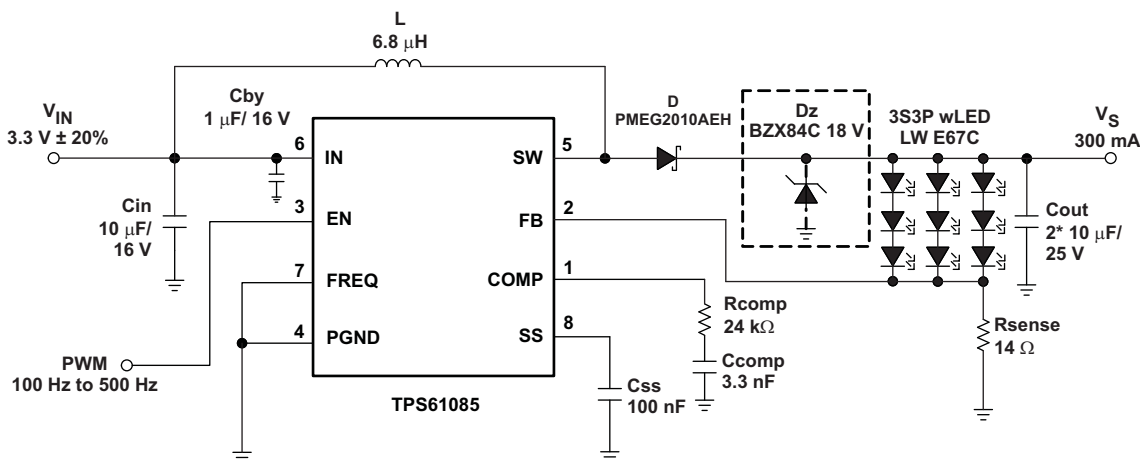


Figure 19. Simple Application (3.3V input - $f_{sw} = 650$ kHz) for wLED Supply (3S3P) with Adjustable Brightness Control using a PWM Signal on the Enable Pin (with optional clamping Zener diode)

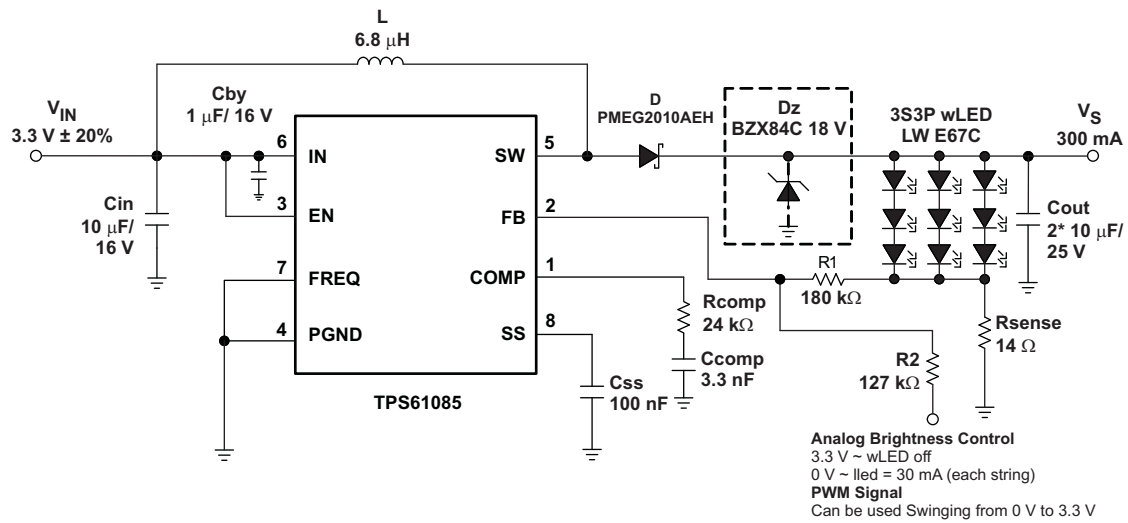


Figure 20. Simple Application (3.3V input - $f_{sw} = 650$ kHz) for wLED Supply (3S3P) with Adjustable Brightness Control using an Analog Signal on the Feedback Pin (with optional clamping Zener diode)

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish | MSL Peak Temp (3) | Op Temp (°C) | Top-Side Markings (4) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-------------------------|------------------|----------------------|--------------|--------------------------|-------------------------|
| TPS61085TDGKR | ACTIVE | VSSOP | DGK | 8 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 105 | PTQI | Samples |
| TPS61085TPWR | ACTIVE | TSSOP | PW | 8 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 105 | 61085T | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

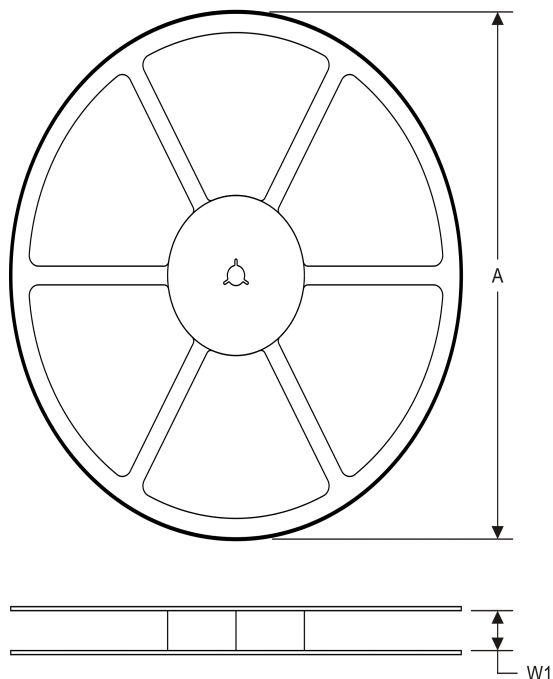
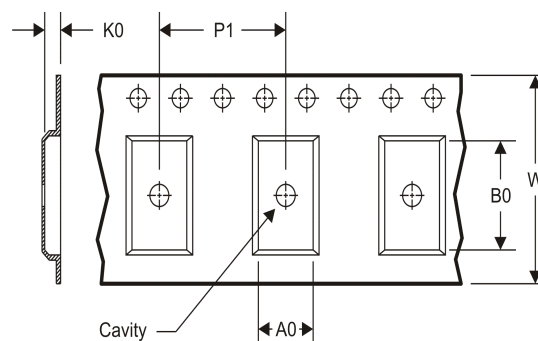
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


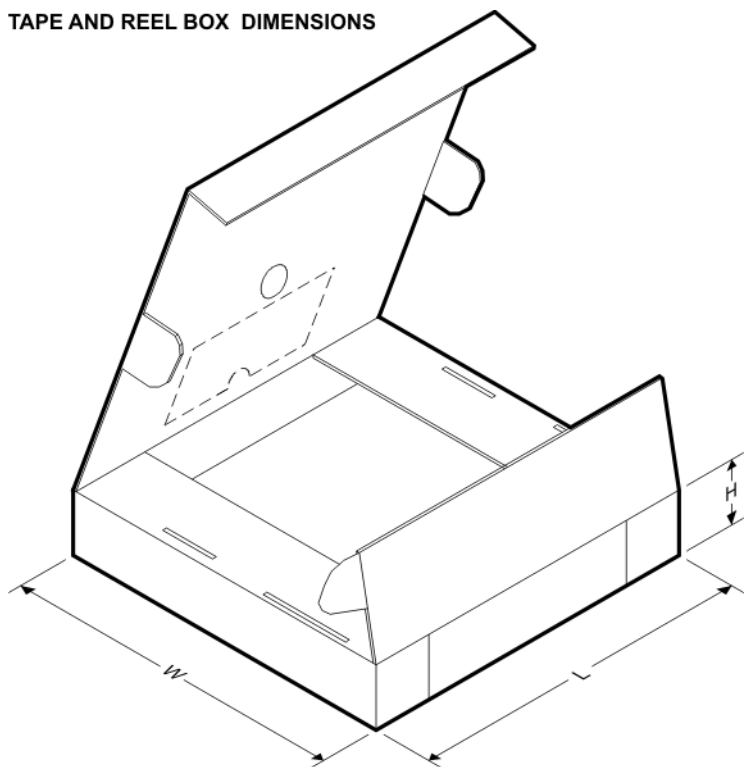
| | |
|----|---|
| A0 | Dimension designed to accommodate the component width |
| B0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

TAPE AND REEL INFORMATION

*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|---------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| TPS61085TDGKR | VSSOP | DGK | 8 | 2000 | 330.0 | 12.4 | 5.3 | 3.4 | 1.4 | 8.0 | 12.0 | Q1 |
| TPS61085TPWR | TSSOP | PW | 8 | 2000 | 330.0 | 12.4 | 7.0 | 3.6 | 1.6 | 8.0 | 12.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS

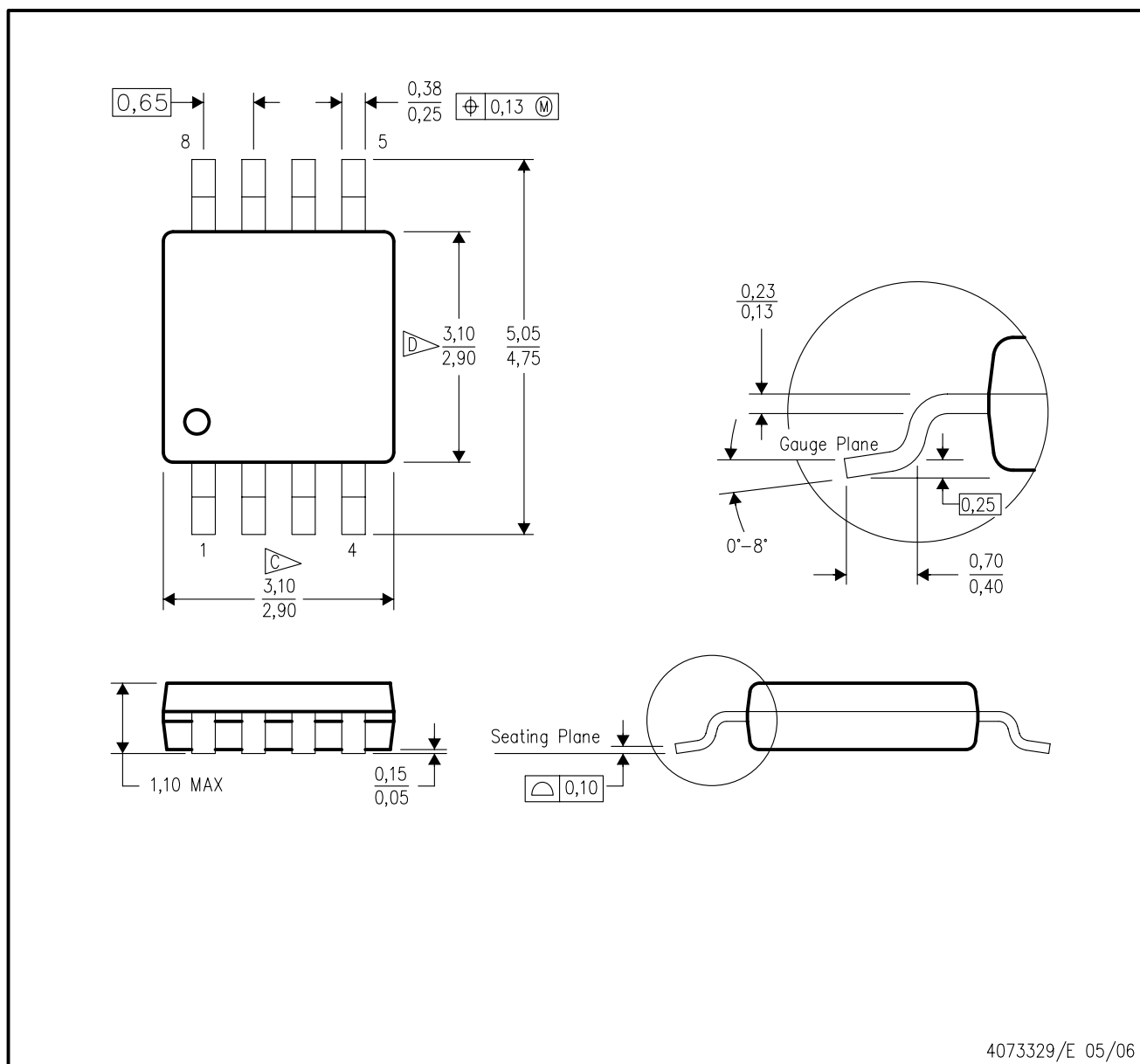


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|---------------|--------------|-----------------|------|------|-------------|------------|-------------|
| TPS61085TDGKR | VSSOP | DGK | 8 | 2000 | 367.0 | 367.0 | 35.0 |
| TPS61085TPWR | TSSOP | PW | 8 | 2000 | 367.0 | 367.0 | 35.0 |

DGK (S-PDSO-G8)

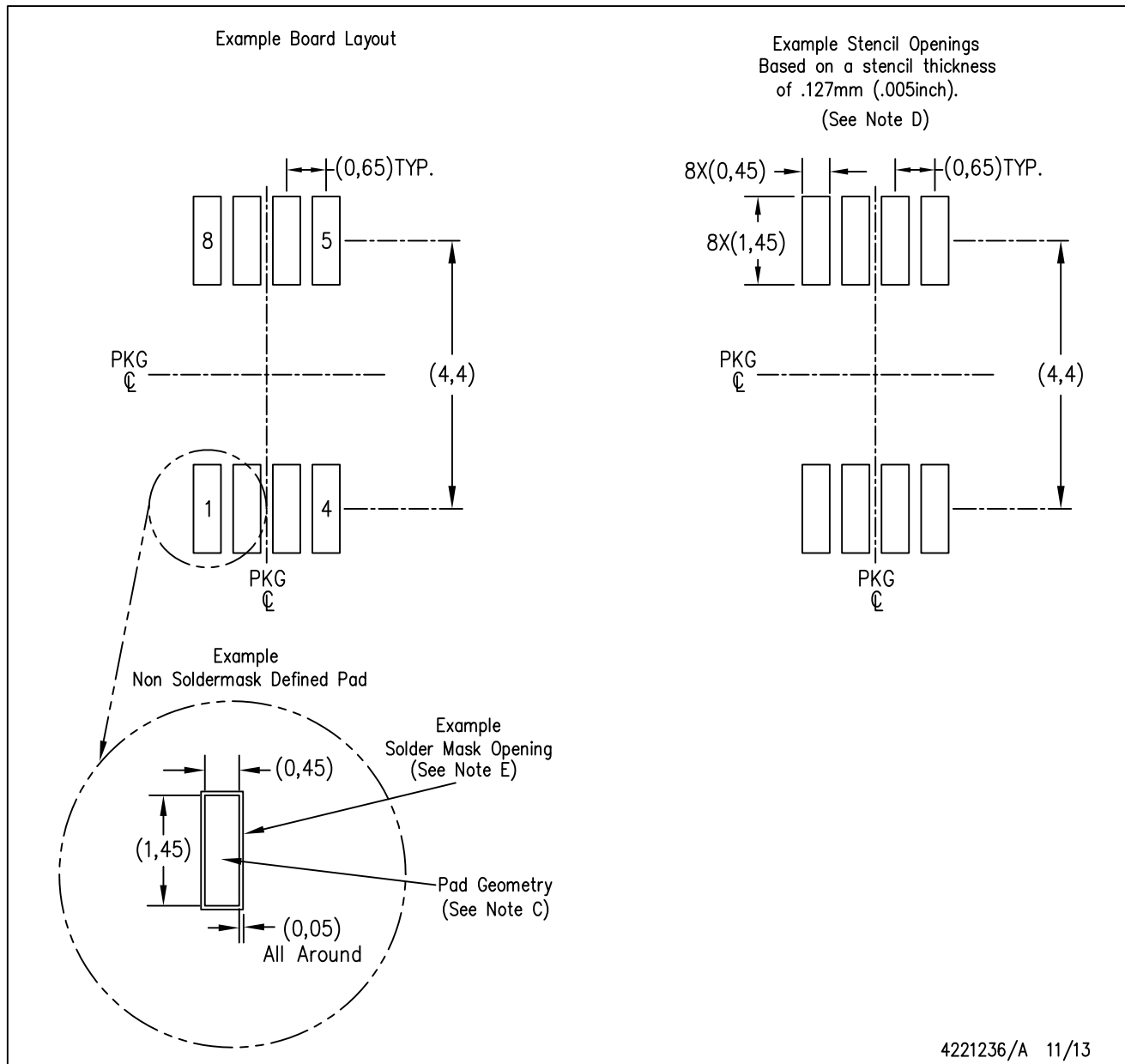
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 per end.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.50 per side.
 - E. Falls within JEDEC MO-187 variation AA, except interlead flash.

DGK (S-PDSO-G8)

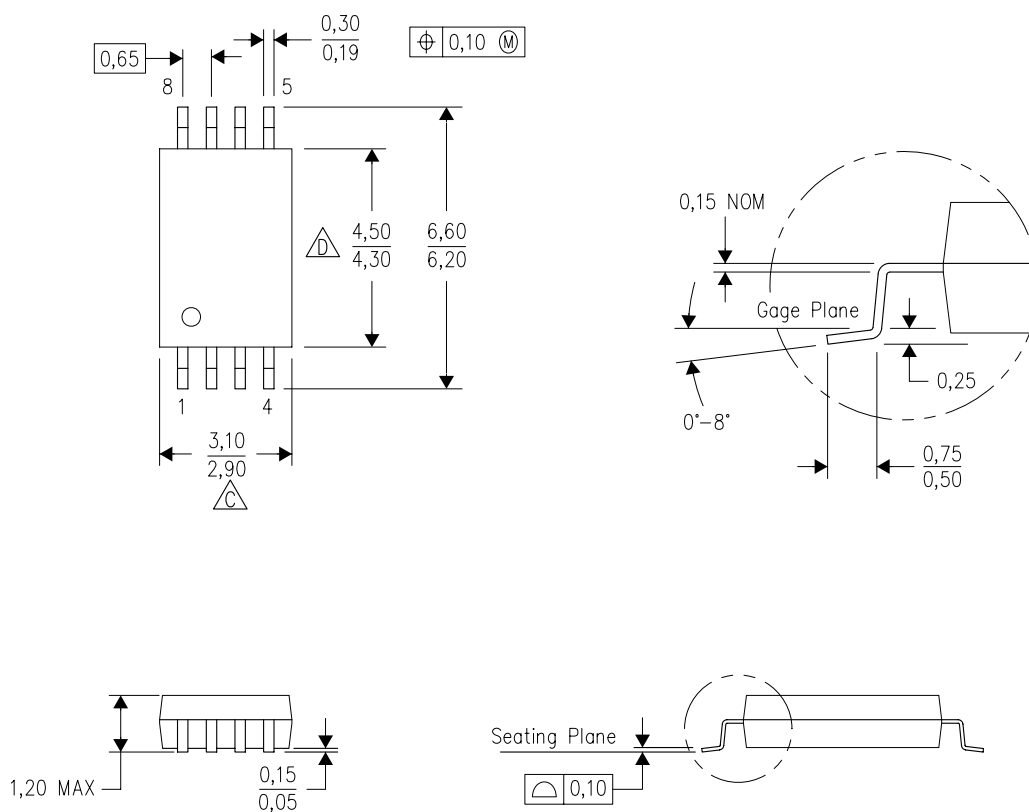
PLASTIC SMALL OUTLINE PACKAGE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G8)

PLASTIC SMALL OUTLINE



4040064-2/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

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